


REVISIONS					
ZONE	REV.	DESCRIPTION	DATE	APPROVED	ECN NO.
	A	ORIGINAL RELEASE	12/15/21	SS	

- NOTES
- MATERIALS:
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.
 - FINISH:
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICROINCHES (2.5um-7.6um) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICROINCHES (1um-2um) THICK).
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
 - PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
 - UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.
 - PACKAGE CONFORMS TO JEDEC MO-220



PROPRIETARY AND CONFIDENTIAL

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		UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: ANGULAR: ±0.5 degree .X = ±0.10 .XX: ±0.05		NAME	DATE	<div><div>QPTechnologies A DIVISION OF PROMEX INDUSTRIES QPTECHNOLOGIES.COM</div></div> <div>TITLE: QP-QFN 36-6MM-0.50MM WITH MINILOCKS</div>			
			DRAWN	S. SWEN	12/15/21				
			CHECKED	S.SWEN	12/15/21				
			ENG APPR.	S.SWEN	12/15/21				
			COMMENTS:						
		MATERIAL				SEE NOTE 1	SIZE	DWG. NO.	REV
NEXT ASSY	USED ON	FINISH				SEE NOTE 2	B	501582	A
APPLICATION		DO NOT SCALE DRAWING				SCALE: 10:1	WEIGHT:	SHEET 1 OF 1	